

## Description

The HSBB1260 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

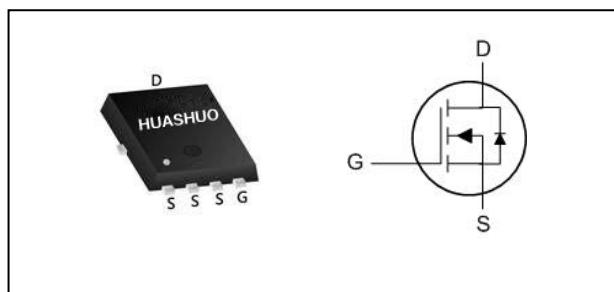
The HSBB1260 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Battery protection
- Power management

## Product Summary

$V_{DS}$	12	V
$R_{DS(ON),typ}$	1.8	$m\Omega$
$I_D$	100	A

## PRPAK3\*3 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	12	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	100	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	70	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	400	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	300	mJ
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	62	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	60	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.0	$^\circ C/W$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	12	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.028	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=4.5\text{V}$ , $I_D=20\text{A}$	---	1.8	2.2	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=15\text{A}$	---	2.2	2.6	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	0.4	0.7	1.0	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-6.16	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=12\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=12\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=20\text{A}$	---	3.5	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.5	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=6\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	37	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	4.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=6\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $R_C=3.3\Omega$	---	21	---	ns
$T_r$	Rise Time		---	45	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	79	---	
$T_f$	Fall Time		---	23	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=6\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	5050	---	pF
$C_{\text{oss}}$	Output Capacitance		---	1060	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	940	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	100	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	400	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=20\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.0	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	18	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	5	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=10\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$
- 4.The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



Typical Characteristics

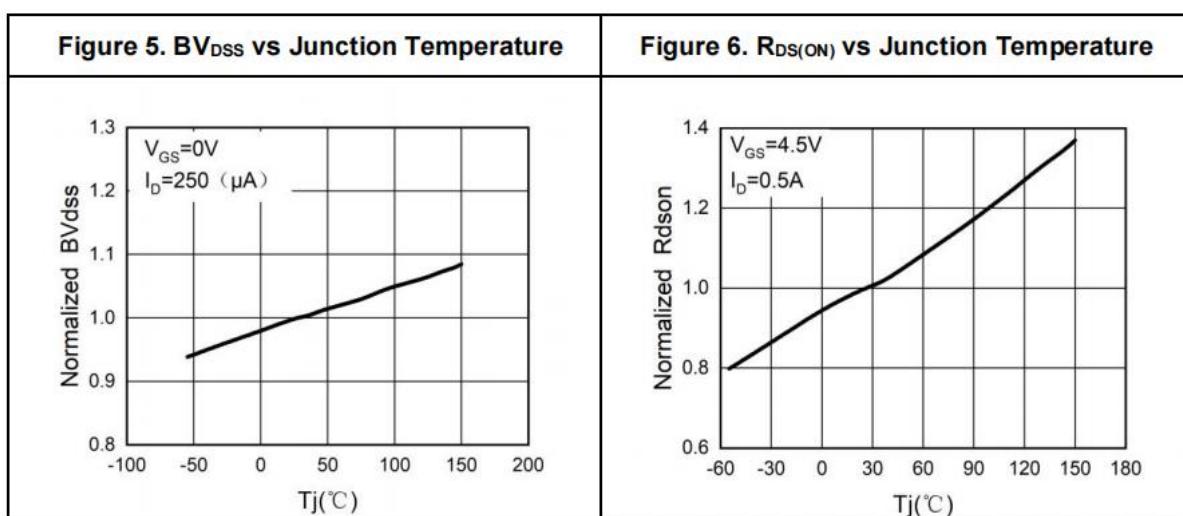
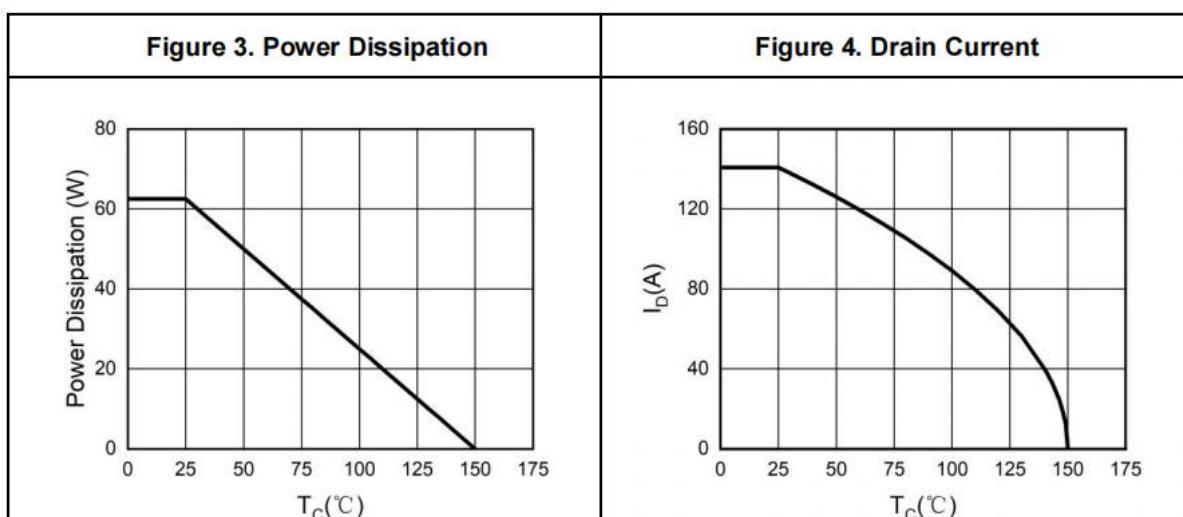
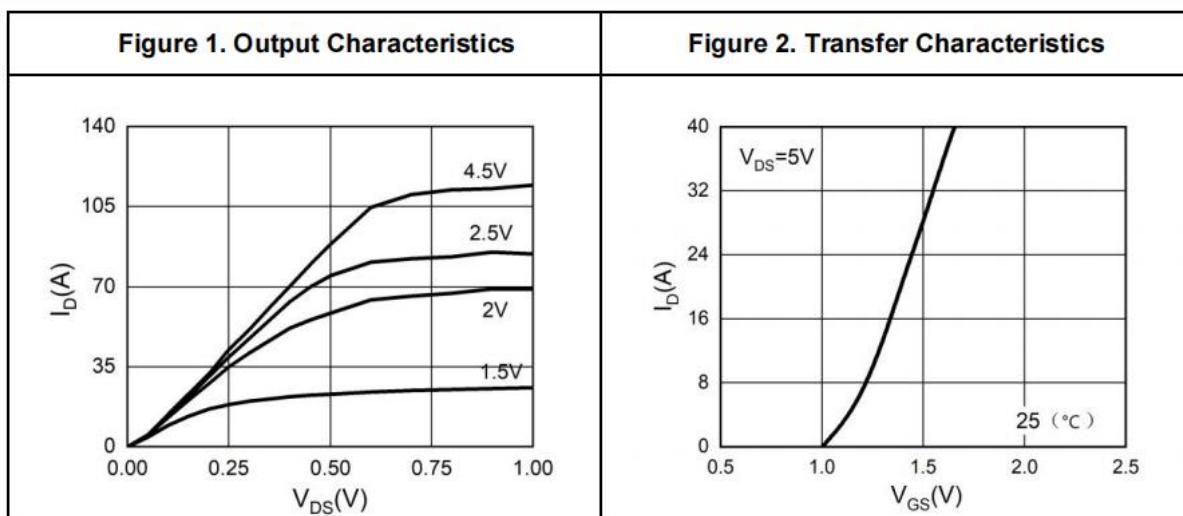




Figure 7. Gate Charge Waveforms

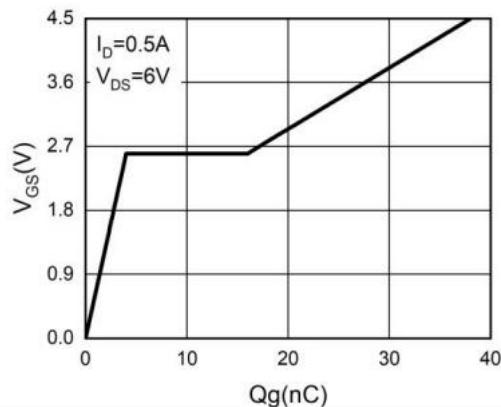


Figure 8. Capacitance

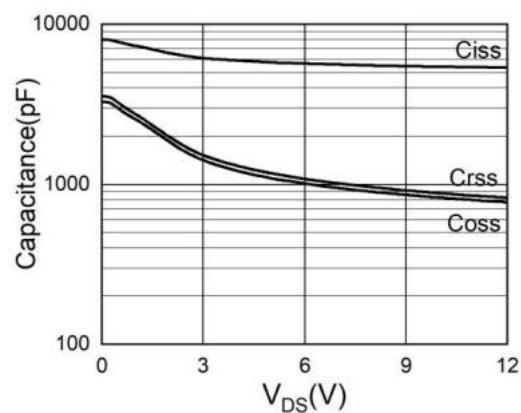


Figure 9. Body-Diode Characteristics

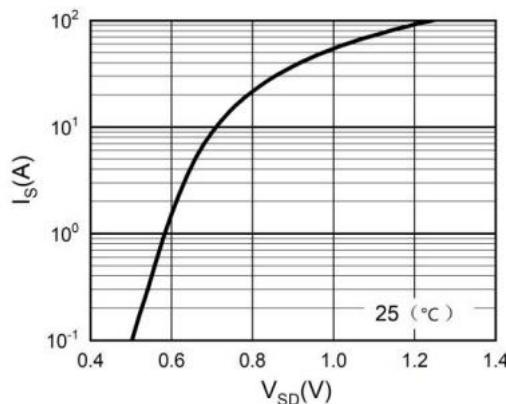
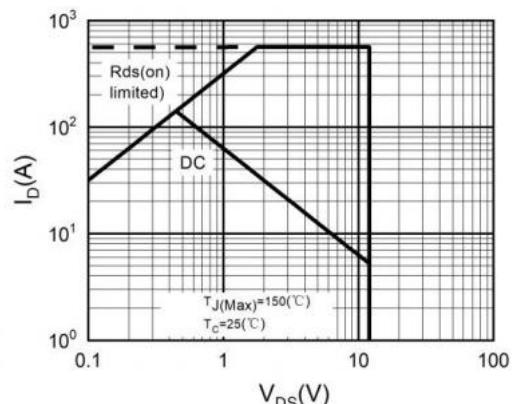
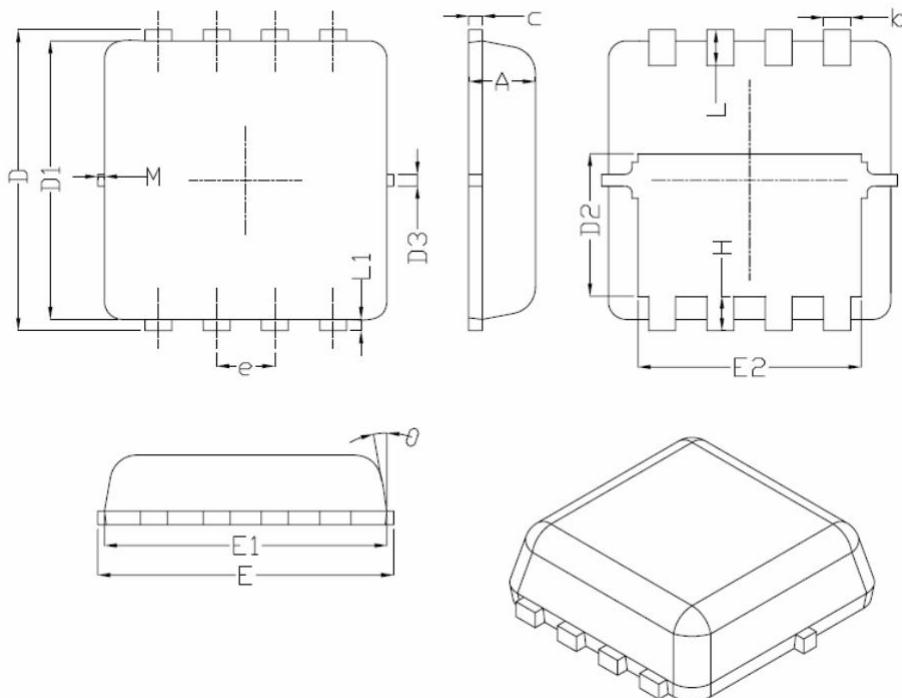


Figure 10. Maximum Safe Operating Area



## Ordering Information

Part Number	Package code	Packaging
HSBB1260	PRPAK3*3	3000/Tape&Reel



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.15	3.30	3.45
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°